	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
1	BRS	36	substrate with metal with plate with reinforce$6 with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:44				S2
2	BRS	3	substrate with metal with plate with reinforce$6 with resin and bond$ with chip with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/08 12:06				S3
3	BRS	13	substrate with metal with plate with resin and reinforce$6 and bond$ with chip with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:31				S4
4	BRS	5	substrate and second with metal with plate with reinforce$6 and bond$ with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:34				S5

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
5	BRS	3	substrate and second with metal with plate with reinforce$6 and bond$ with chip and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:34				S6
6	BRS	24	second with metal with plate with reinforc$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 20:36				S7
7	BRS	20	second with metal with plate with reinforc$6 and semiconductor and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:16				S8
8	BRS	17	("3601753" | "4028509" | "4096577" | "4197586" | "4328399" | "4456800" | "4567354" | "4611261").PN. OR ("4675787").URPN.	US-PGPUB; USPAT; USOCR	2005/03/19 21:10				S9

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
9	BRS	36	("3710193" | "4074342" | "4296456" | "4533976" | "4677526" | "4766520" | "4802859" | "4873615" | "4916575" | "4985747" | "4989318" | "5031069" | "5045971" | "5081764" | "5157588").PN. OR ("5408383").URPN.	US-PGPUB; USPAT; USOCR	2005/03/19 21:13				S10
10	BRS	6	metal with plate with reinforc$6 with pressure and semiconductor and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:20				S11
11	BRS	27	(metal or plate) with reinforc$6 with pressure with resin and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:40				S12

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
12	BRS	4	upper with lower with reinforc$6 with pressure with resin and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:42				S13
13	BRS	4	upper with lower with reinforc$6 with pressure and resin with seal$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:43				S14
14	BRS	49	upper with lower with plate with pressure and resin with seal$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 21:44				S15
15	BRS	49	("3729573" | "4377548" | "4470786" | "4626185" | "4823234" | "4954307").PN. OR ("5091341").URPN.	US-PGPUB; USPAT; USOCR	2005/03/19 22:11				S16

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
16	BRS	32	(("3729573" | "4377548" | "4470786" | "4626185" | "4823234" | "4954307").PN. OR ("5091341").URPN.) and (pressure or force)	US-PGPUB; USPAT; USOCR	2005/03/19 22:11				S17
17	BRS	21	(("3729573" | "4377548" | "4470786" | "4626185" | "4823234" | "4954307").PN. OR ("5091341").URPN.) and (pressure or force) and plate	US-PGPUB; USPAT; USOCR	2005/03/19 22:12				S18
18	BRS	12	substrate with metal with plate with reinforce$6 and resin with (seal$6 or encapsulat$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:26				S19

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
19	BRS	93	substrate and plate with reinforce$6 and resin with (seal$6 or encapsulat$6) and (pressure or force) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:28				S21
20	BRS	9)	substrate and metal with plate with reinforce$6 and resin with (seal$6 or encapsulat$6) and (pressure or force) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:30				S22

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
21	BRS	6	substrate with metal with plate with (force or pressure) and resin with (seal$6 or encapsulat$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:24				S24
22	BRS	96	substrate with (metal or plate) with (force or pressure) and resin near (seal$6 or encapsulat$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 22:34				S25

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
23	BRS	96	substrate with (metal or plate) with (force or pressure) and resin near (seal$6 or encapsulat$6) and (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 23:04				S26
24	BRS	5	reinforc$6 with (metal or plate) with (force or pressure) and resin near (seal$6 or encapsulat$6) with (integrated near circuit or IC) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/19 23:05				S28

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
25	BRS	50	("4447716" | "4649418" | "4682017" | "4725924" | "4731645" | "4731700").PN. OR ("4962415").URPN.	US-PGPUB; USPAT; USOCR	2005/03/19 23:14				S29
26	BRS	18	(substrate or plate) with reinforce$6 with resin with (seal$6 or encapsulat$6) with (pressure or force)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:13				S30
27	BRS	75	(substrate or plate) with reinforce$6 same resin same (seal$6 or encapsulat$6) same (pressure or force)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 15:51				S31

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
28	BRS	66	(438/124).ccls. and resin with (seal$6 or encapsulat$6) and reinforc$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 12:41				S32
29	BRS	8	"5200601"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 15:17				S33
30	BRS	6	("3622419" | "4849803" | "4994659" | "5200601" | "5898215").PN. OR ("6069402").URPN.	US-PGPUB; USPAT; USOCR	2005/03/25 15:46				S34
31	BRS	26	(substrate or plate) with reinforce$6 same resin same (seal$6 or encapsulat$6) same (compress$6 or thermocompress$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:11				S35

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
32	BRS	15	resin with (seal$6 or encapsulat$6) same (compress$6 or thermocompress$6) with reinforc$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:18				S36
33	BRS	71	resin with (seal$6 or encapsulat$6) same (compress$6 or thermocompress$6 or press$6 or force) with reinforc$6 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:19				S37

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
34	BRS	44	substrate with (metal or plate) with reinforce$6 with resin and (saw$6 or dic$6 or singulat$6 or separat$6) and reinforc$6 with (pressur$6 or compress$6 or thermocompress$6 or forc$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:57				S38
35	BRS	91	(saw$6 or dic$6 or singulat$6 or separat$6) with (wafer or substrate) and (compress$6 or thermocompress$6) with resin with seal$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 16:59				S39

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors	Ref #
36	BRS	40	(saw$6 or dic$6 or singulat$6 or separat$6) with (wafer or substrate) and (compress$6 or thermocompress$6) with resin with seal$6 and (support$ or reinforc$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/25 17:00				S40

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	1	card with roll near film with coat$4 same heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4 or separat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:52			
2	BRS	L4	5	card with film with coat$4 with heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4 or separat$5) and roll$4 near film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:49			
3	BRS	L5	1	card with roll$5 near film with coat$4 same heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4 or separat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:53			
4	BRS	L6	9	card with roll$5 near film same heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4 or separat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 14:53			
5	BRS	L9	34	card with roll$4 with film with heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 15:28			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
6	BRS	L12	23	card with roll$4 with film with heat$6 and (divid$4 or saw$5 or dic$4 or singulat$4 or separat$5 or separat$5) near card	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/03/26 15:45			